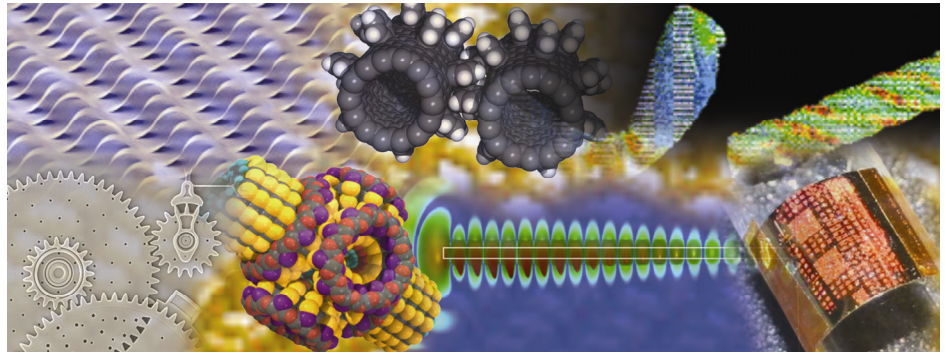




Institute of Electrical and Electronics Engineers, Inc.

**Phoenix Section
Components, Packaging and
Manufacturing Technology
Society Chapter
&
Waves and Devices Chapter**

*PRESENT AN ALL-DAY
WORKSHOP ON*



Images courtesy of Argonne National Laboratory, NASA Ames Center for Nanotechnology, Stanford University, Sandia National Laboratories (SUMMIT™ Technologies) and Nanorex, Inc.

Emerging Device and Packaging Technologies

Friday, November 14th, 2008 7:00 A.M. – 5:00 P.M.

Arizona State University, Tempe, Arizona – ASU Memorial Union (Arizona Room)

EXECUTIVE COMMITTEE

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Kalluri Sarma, Honeywell
Sudhama Shastri, CMD
Sandeep Tonapi, Anveshak

Call for Papers

The continued scaling of microelectronics for mainstream applications such as computing and communications on one hand has been enabled by newly developed materials, tools, and techniques; on the other hand the associated capabilities are spawning novel applications and market opportunities. This year's one-day workshop focuses on the topics of nanotechnology, bioelectronics, and energy. Invited experts from industry, academia, research labs, and consortia will share their vision of technical challenges and opportunities in these areas. Current and emerging device, interconnect, and packaging technologies will be discussed in depth. A poster session on the broader workshop topic of emerging device and packaging technologies has been added this year to provide additional presentation and discussion opportunities. Select vendors will exhibit products and services related to all aspects of the supply chain for microelectronics design and manufacturing.

Invited Speaker Topics

Nanotechnology

- Nanofabrication
- Nanoelectromechanical Systems
- Nanofluidic Devices

Bioelectronics

- Biochips
- Biosensing
- Biosecurity

Energy

- Solar Cells
- Energy Harvesting
- Micro Power Generators

Poster Session

Abstracts are invited for consideration to the poster session in emerging device and packaging technologies (not limited to nanotechnology, bioelectronics, or energy).

Poster Abstract Submissions: Two pages (topic, summary of significant results and conclusions – WORD or PDF files only). Abstract must include author names, affiliations, addresses, and e-mail address of lead author.

Submission Deadline:	August 29, 2008
Submitting Address:	melmiller@ieee.org
Acceptance Notification:	September 19, 2008
Final Presentation Due:	November 5, 2008

Sponsorships and Vendor Displays: This is a great opportunity to promote your company or product. For more information, contact Vasu Atluri vpatluri@ieee.org or Chuck Weitzel c.weitzel@ieee.org (sponsors) and Steve Rockwell steve.rockwell@ieee.org (vendors).

Workshop Registration: On-line registration will open in August at www.acteva.com/go/ieeephxsecworkshop2008